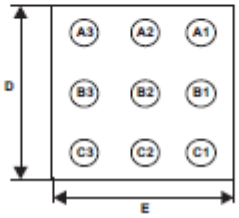
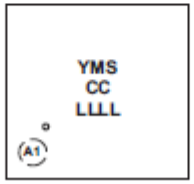
PACKAGE SUMMARY

CHIP SCALE PACKAGE
(BOTTOM VIEW)



CHIP SCALE PACKAGE
(TOP VIEW)



Code:

- YM - 2 digit date code
- S - assembly site code
- CC - chip code (see ordering table)
- LLLL - lot trace code

PACKAGE DIMENSIONS

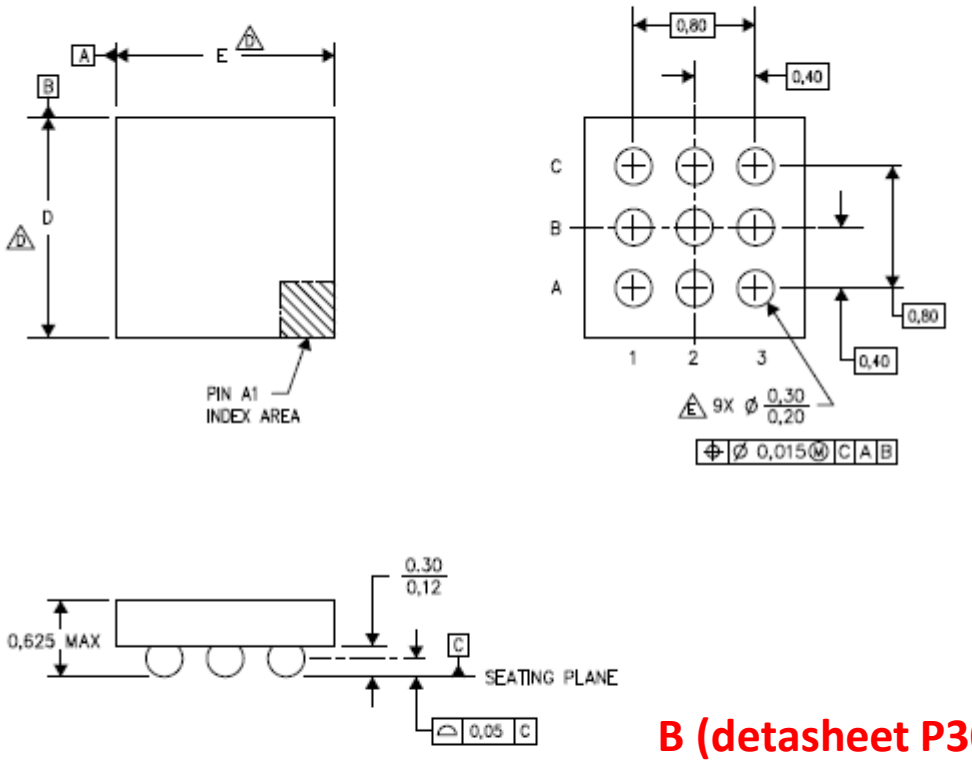
The dimensions for the YFF-9 package are shown in Table 5. See the package drawing at the end of this data sheet.

A (detasheet P26)

Table 5. YFF-9 Package Dimensions

Packaged Devices	D	E
TPS6125xYFF	1.206 ±0.03 mm	1.306 ±0.03 mm

YFF (S–XBGA–N9) DIE–SIZE BALL GRID ARRAY



B (detasheet P30)

D: Max = 1.356 mm, Min =1.256 mm

E: Max = 1.256 mm, Min =1.156 mm

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NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
- B. This drawing is subject to change without notice.
- C. NanoFree™ package configuration.
- D. The package size (Dimension D and E) of a particular device is specified in the device Product Data Sheet version of this drawing, in case it cannot be found in the product data sheet please contact a local TI representative.
- E. Reference Product Data Sheet for array population. 3 x 3 matrix pattern is shown for illustration only.
- F. This package contains Pb–free balls.